



FINAL AGENDA

7:45 Registration opens

Session 1 –Market Drivers and Supply Chain Collaboration

Session Leader: Dan Tracy, D.P. Tracy Associates

9:00 am -9:30 am **KEYNOTE: Heterogeneous Integration: is it ready for changing the packaging landscape?**

Risto Puhakka, President, VLSI Research

9:30 am – 10:00 am **Cost Effective Solutions for System Integration**

Dr. Dongkai Shangguan, Vice President for Advanced Manufacturing Engineering, Flex

10:00 am – 10:30 am **Why Heterogenous Integration? The Answer is Economics!**

E. Jan Vardaman, President, TechSearch International, Inc.

10:30 am – 11:00 am **Break in Exhibit Area**

Session 2 – Design and Test of Chiplelets and Multi-die ICs

Session Leader: Herb Reiter, eda 2 asic Consulting, Inc.

11:00 am – 11:30 am **KEYNOTE: Disruption is Coming: Adapt, Change or Be Left Behind**

Keith Felton, Product Marketing – IC Packaging, Mentor Graphics Board Systems Division

11:30 am –12:00 pm **Design and Manufacturing – From Silos to Strategic Collaboration**

Bob Smith, Executive Director, ESD Alliance (a SEMI Strategic Association Partner), Bettina Weiss, Vice President Business Development, SEMI

12:00 pm – 12:30 pm **As the Industry Starts to Look Away from SOC and Towards Heterogenous Integration, What New Challenges are Emerging for Design and Test?**

John Park, Product Management Director, IC Packaging and Cross-Platform Solutions, Cadence Design Systems and Lisa Jensen, Product Engineering Director, Modus DFT Software Solutions, Cadence Design Systems

12:30 pm – 1:30 pm **Lunch**

Session 3 - The Manufacturing Challenges of Heterogeneous Packaging

Session Leader: Joel Camarda, Altierre

- 1:30 pm – 2:00 pm **KEYNOTE: Heterogeneous Integration Roadmap – Driving Force and Enabling Technologies for Systems of the Future**
Rich Rice, Senior Vice President of Sales, ASE (U.S.) Inc.
- 2:00 pm – 2:30 pm **Advancements in Assembly Equipment for Heterogeneous Integration**
Horst Clauberg, Director of Advanced Packaging Process Engineering
Kulicke & Soffa Industries, Inc.
- 2:30 pm – 3:00 pm **Building Blocks of Heterogeneous SoCs**
Chris Scanlan, Vice President, Product Management & Engineering
Deca Technologies
- 3:00 pm – 3:30 pm **Break in Exhibit Area**
- 3:30 pm – 5:00 pm **Panel: Supply Chain Issues for Advanced Packaging**
Moderator: Ed Sperling, founder and Editor-in-Chief, Semiconductor Engineering Magazine
Organizer: Herb Reiter, eda 2 asic Consulting, Inc.

Panelists:

- **Chenglin Liu**
Director, Packaging Engineering, Marvell
- **Juan Rey**
Vice president of Engineering, Calibre, Mentor
- **Rich Rice**
Senior Vice President of Sales for ASE (U.S.)
- **Eric Tosaya**
Senior Director Package Manufacturing, eSilicon

5:00 pm – 6:30 pm Reception in Exhibits area

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